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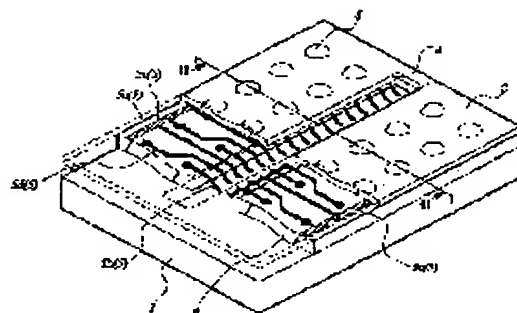
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(54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREFOR

(57)Abstract:

PROBLEM TO BE SOLVED: To facilitate the standardization of in the number of outer leads, the improvement of the performance and the standardization of an input/output terminal arrangement in an area-array-type surface-mounting semiconductor device, wherein a TCP(tape-carrier package) tape is applied.

SOLUTION: A tape substrate 2, wherein copper or copper alloy is a main conductor layer and a gold-plated wiring 5 is provided on the surface, and a semiconductor chip 1 are bonded by a bonding layer 8 composed of an elastic body. Connection is performed to the wiring connecting part on the semiconductor chip 1 by an inner lead part 5b of the wiring 5. In this semiconductor device, a common wiring part 5c, which is grounded or held at a power supply potential, is provided in the wiring 5. A lead wiring part 5d, which is connected directly to the inner lead 5b from the common wiring part 5c, without going through a land part 5a for an external electrode, is provided.



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